

### Features

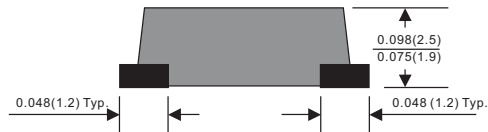
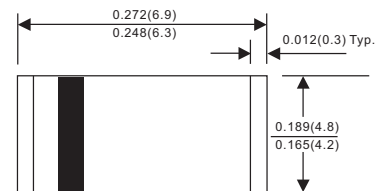
- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SMC-L
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.19 gram

### Package outline

SMC $\bar{L}$



Dimensions in inches and (millimeters)

### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	$I_o$			3.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	$I_{FSM}$			80	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^\circ\text{C}$	$I_R$			1.0	mA
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_j$		300		pF
Storage temperature		$T_{STG}$	-55		+150	$^\circ\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ )
SL32-L	20	14	20	0.38	-55 to +100
SL34-L	40	28	40	0.40	

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

\*4 Maximum forward voltage@ $I_F=3.0\text{A}$

**Rating and characteristic curves**

FIG.1-TYPICAL FORWARD

CHARACTERISTICS

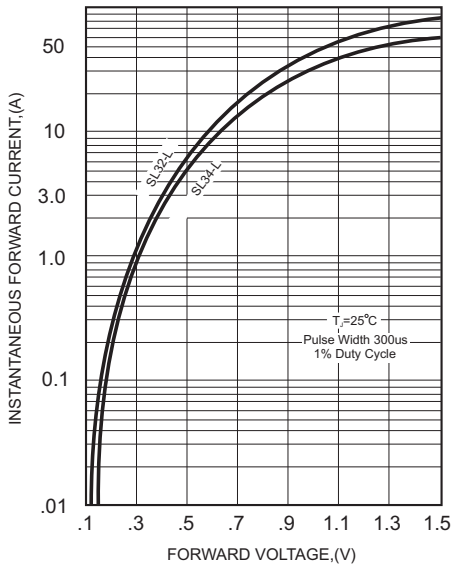


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

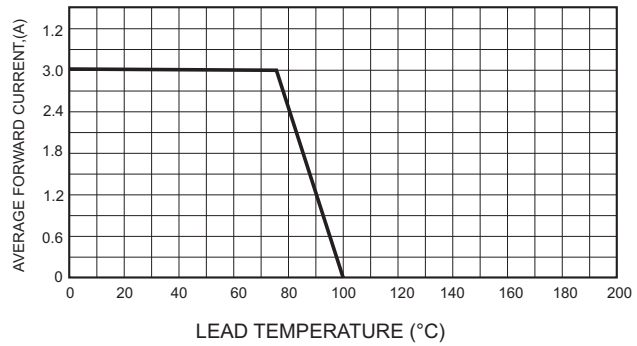


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

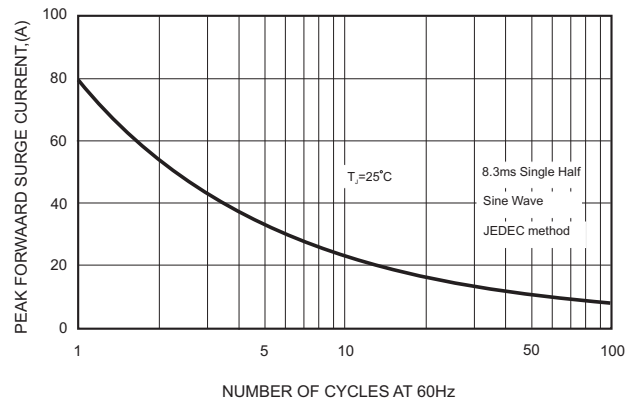


FIG.3 - TYPICAL REVERSE

CHARACTERISTICS

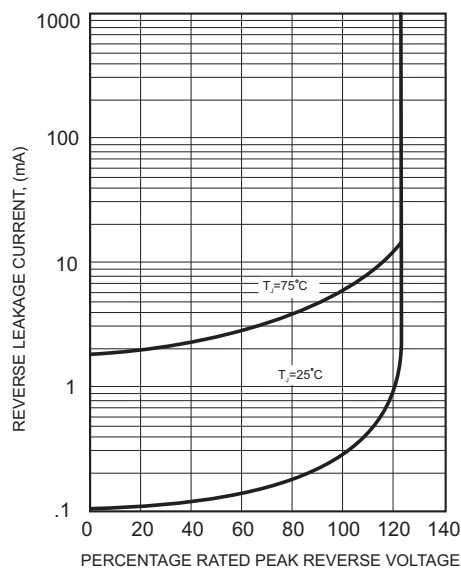
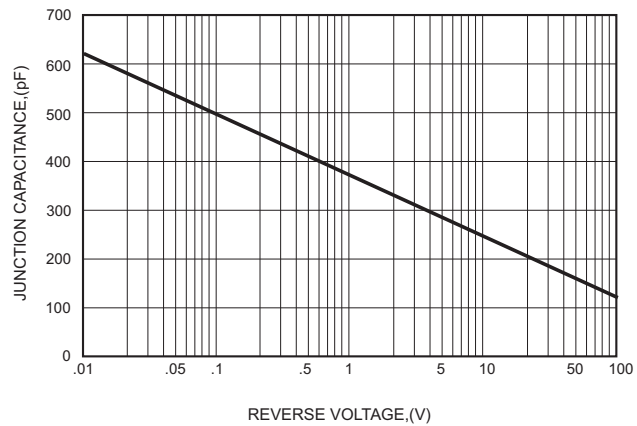


FIG.5-TYPICAL JUNCTION CAPACITANCE



**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

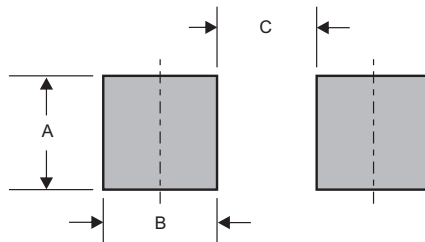
**Reel packing**

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC $\overline{\text{L}}$	13"	3,000	8.0	6,000	337*337*37	330	350*330*360	48,000	17.2

**Marking**

Type number	Marking code
SL32-L-TH	SL32
SL34-L-TH	SL34

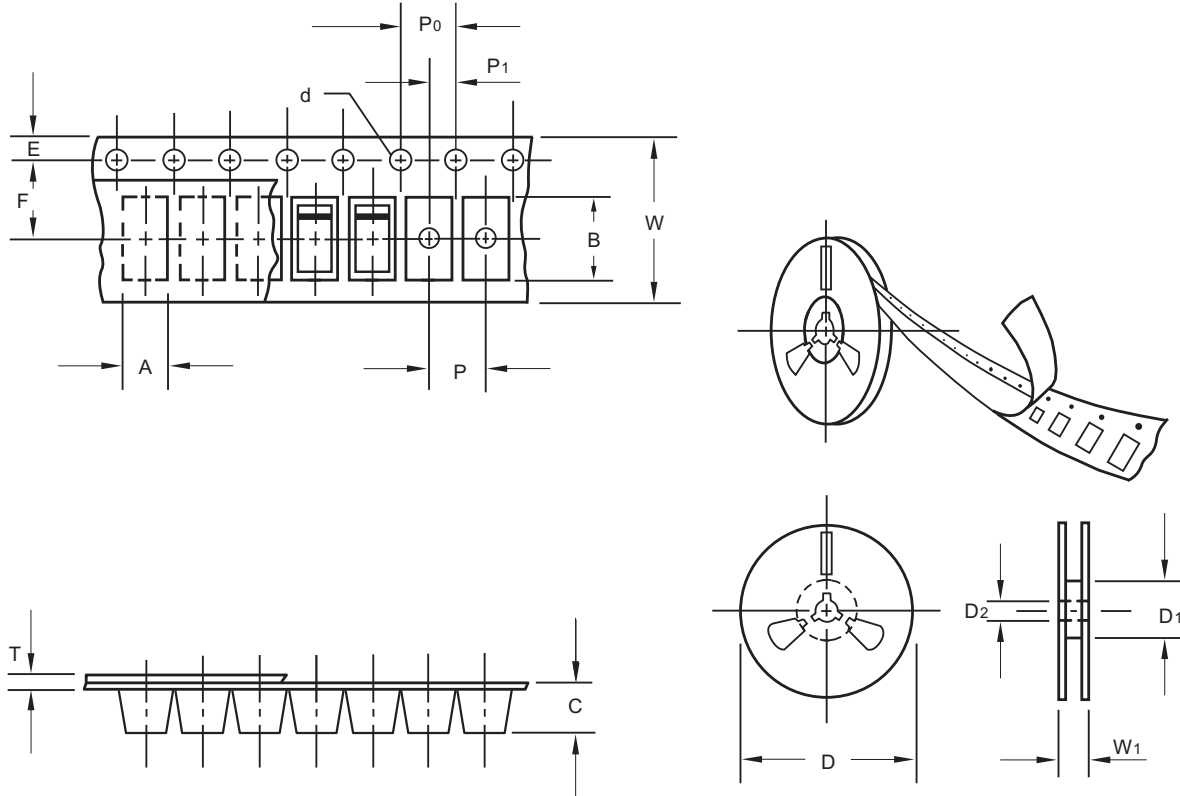
**Suggested solder pad layout**



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC-L	0.189 (4.80)	0.063 (1.60)	0.158 (4.00)

**Packing information**



unit:mm

Item	Symbol	Tolerance	SMC-L
Carrier width	A	0.1	5.10
Carrier length	B	0.1	7.20
Carrier depth	C	0.1	2.50
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.